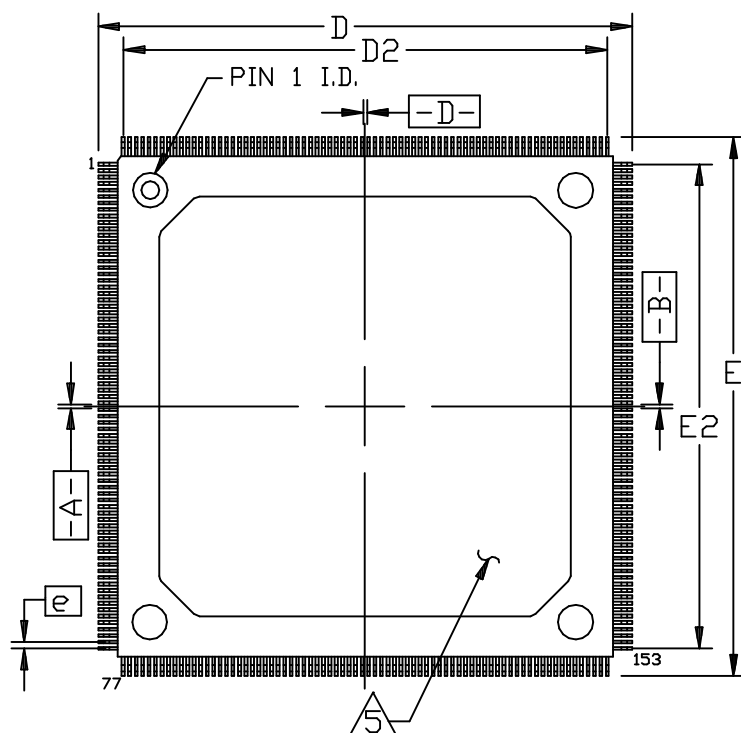
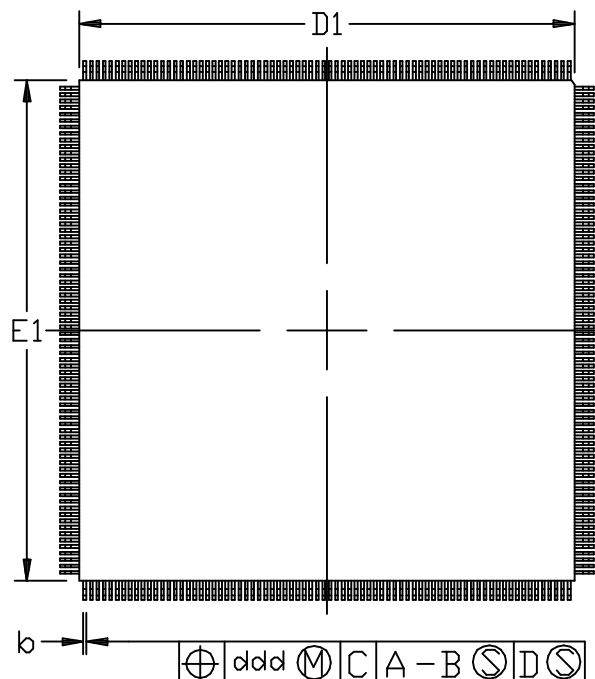


TOP VIEW



BOTTOM VIEW

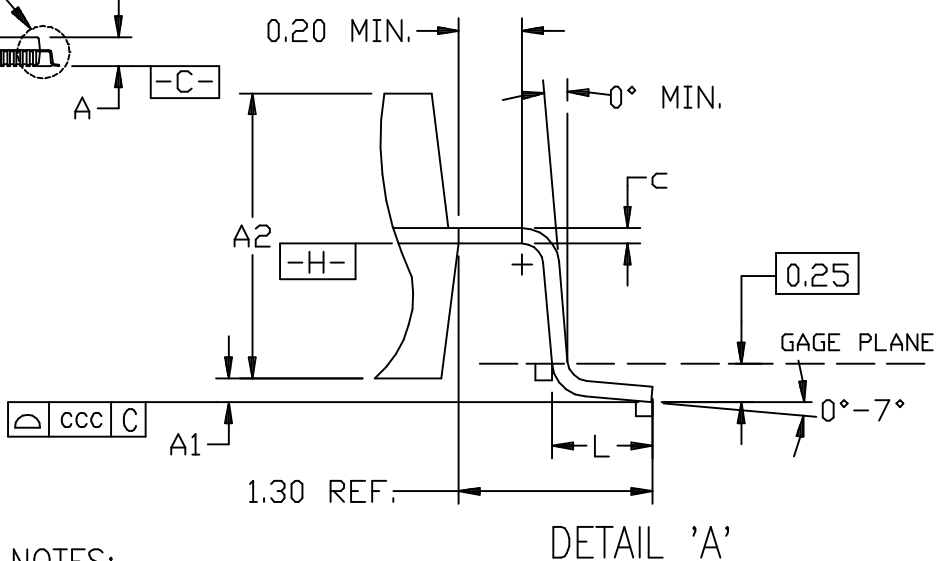


5°-16°

SEE DETAIL 'A'

LEAD FINISH: SOLDER PLATE

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	$\sim$	4.23	4.50
A <sub>1</sub>	0.25	0.43	$\sim$
A <sub>2</sub>	3.60	3.80	4.00
D/E	42.60 BSC		
D <sub>1</sub> /E <sub>1</sub>	40.00 BSC		
D <sub>2</sub> /E <sub>2</sub>	37.50 REF.		
L	0.45	0.60	0.75
e	0.50 BSC.		
b	0.17	$\sim$	0.27
b <sub>1</sub>	$\sim$	0.20	$\sim$
ccc	0.08		
ddd	0.07		



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982
  2. DIMENSIONS "D1" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.
  3. PACKAGE TOP DIMENSIONS MAY BE SMALLER THAN BOTTOM DIMENSIONS BY 0.15mm.
  4. CONFORMS TO JEDEC OUTLINE MO-143-JA
- △ THE SAME PACKAGE DIMENSIONS APPLY FOR THERMALLY ENHANCED PRODUCTS. HEAT SINK IS ADDED. THE PACKAGE CODE IS "HQ".

304-PIN PQFP (PQ304)  
304-PIN HEAT SINK PQFP (HQ304)